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October 1995 Revised May 2003

74LCX2244

Low Voltage Buffer/Line Driver with 5V Tolerant Inputs and Outputs with 26 Ω Series Resistors in the Outputs

General Description

The LCX2244 contains eight non-inverting buffers with 3-STATE outputs. The device may be employed as a memory address driver, clock driver and bus-oriented transmitter/receiver. The LCX2244 is designed for low voltage (2.5V or 3.3V) $V_{\rm CC}$ applications with capability of interfacing to a 5V signal environment. The 26Ω series resistors help reduce output overshoot and undershoot.

The LCX2244 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant inputs and outputs
- 2.3V to 3.6V V_{CC} specifications provided
- \blacksquare 7.5 ns t_{PD} max (V_{CC} = 3.3V) 10 μ A I_{CC} max
- Power down high impedance inputs and outputs
- 26Ω -series resistors in the outputs
- Supports live insertion/withdrawal (Note 1)
- ± 12 mA output drive ($V_{CC} = 3.0V$)
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:

Human body model > 2000V Machine model > 200V

■ Leadless DQFN package

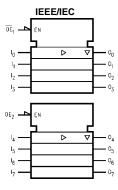
Note 1: To ensure the high-impedance state during power up or down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

Ordering Code:

Order Number	Package Number	Package Description
74LCX2244WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LCX2244SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LCX2244BQ (Preliminary)		20-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 4.5mm
74LCX2244MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74LCX2244MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

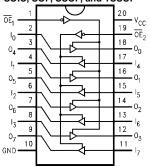
Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

Logic Symbol

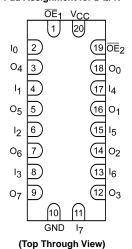


Connection Diagrams

Pin Assignments for SOIC, SOP, SSOP, and TSSOP



Pad Assignment for DQFN



Pin Descriptions

Pin Names	Description
$\overline{OE}_1, \overline{OE}_2$	3-STATE Output Enable Inputs
I ₀ —I ₇	Inputs
O ₀ -O ₇	Outputs

Truth Tables

Inputs		Outputs
OE ₁	I _n	(Pins 12, 14, 16, 18)
٦	L	L
L	Н	Н
Н	Х	Z

Inputs		Outputs
OE ₂	I _n	(Pins 3, 5, 7, 9)
L	L	L
L	Н	Н
Н	Х	Z

H = HIGH Voltage Level
X = Immaterial
L = LOW Voltage Level
Z = High Impedance

Symbol	Parameter	Value	Conditions	Units
V _{CC}	Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	-0.5 to +7.0		V
V _O	DC Output Voltage	-0.5 to +7.0	Output in 3-STATE	V
		-0.5 to $V_{CC} + 0.5$	Output in HIGH or LOW State (Note 3)	v
l _{IK}	DC Input Diode Current	-50	V _I < GND	mA
ок	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	IIIA
О	DC Output Source/Sink Current	±50		mA
СС	DC Supply Current per Supply Pin	±100		mA
GND	DC Ground Current per Ground Pin	±100		mA
T _{STG}	Storage Temperature	-65 to +150		°C

Recommended Operating Conditions (Note 4)

Symbol	Parameter		Min	Max	Units
V _{CC}	Supply Voltage	Operating	2.0	3.6	V
		Data Retention	1.5	3.6	V
V _I	Input Voltage		0.0	5.5	V
Vo	Output Voltage	HIGH or LOW State	0.0	V _{CC}	V
		3-STATE	0.0	5.5	V
I _{OH} /I _{OL}	Output Current	$V_{CC} = 3.0V - 3.6V$		±12.0	
		$V_{CC} = 2.7V - 3.0V$ $V_{CC} = 2.3V - 2.7V$		±8.0	mA
		$V_{CC} = 2.3V - 2.7V$		±4.0	
T _A	Free-Air Operating Temperature		-40.0	85.0	°C
Δt/ΔV	Input Edge Rate, $V_{IN} = 0.8V - 2.0V$, $V_{CC} = 3.0V$		0.0	10.0	ns/V

Note 2: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 3: I_O Absolute Maximum Rating must be observed.

Note 4: Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Cumbal	Parameter	Conditions	v _{cc}	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		Units
Symbol		Conditions	(V)	Min	Max	Units
V _{IH}	HIGH Level Input Voltage		2.3 – 2.7	1.7		V
			2.7 – 3.6	2.0		V
V _{IL}	LOW Level Input Voltage		2.3 – 2.7		0.7	V
			2.7 – 3.6		8.0	V
V _{OH}	HIGH Level Output Voltage	$I_{OH} = -100 \mu A$	2.3 – 3.6	V _{CC} - 0.2		
		$I_{OH} = -4 \text{ mA}$	2.3	1.8		
		$I_{OH} = -4 \text{ mA}$	2.7	2.2		V
		$I_{OH} = -6 \text{ mA}$	3.0	2.4		. •
		$I_{OH} = -8mA$	2.7	2.0		
		I _{OH} = -12 mA	3.0	2.0		
V _{OL}	LOW Level Output Voltage	I _{OL} = 100 μA	2.3 – 3.6		0.2	
		I _{OL} = 4 mA	2.3		0.6	
		I _{OL} = 4 mA	2.7		0.4	V
		I _{OL} = 6 mA	3.0		0.55	. •
		I _{OL} = 8 mA	2.7		0.6	
		I _{OL} = 12 mA	3.0		0.8	
l _l	Input Leakage Current	$0 \le V_I \le 5.5V$	2.3 – 3.6		±5.0	μΑ
I _{OZ}	3-STATE Output Leakage	$0 \le V_O \le 5.5V$	2.3 – 3.6		±5.0	
		$V_I = V_{IH}$ or V_{IL}				μΑ

DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC}	T _A = -40°0	C to +85°C	Units
Cynnbon	i arameter	Conditions	(V)	Min	Max	Oilles
l _{OFF}	Power-Off Leakage Current	V_I or $V_O = 5.5V$	0.0		10.0	μΑ
Icc	Quiescent Supply Current	$V_I = V_{CC}$ or GND	2.3 – 3.6		10.0	μА
		3.6V ≤ V _I , V _O ≤ 5.5V (Note 5)	2.3 – 3.6		±10.0	μΛ
ΔI_{CC}	Increase in I _{CC} per Input	$V_{IH} = V_{CC} - 0.6V$	2.3 – 3.6		500	μΑ

Note 5: Outputs disabled or 3-STATE only.

AC Electrical Characteristics

			T _A =	-40°C to +	85°C, R _L = 5	500Ω		
Cumbal	Parameter	V _{CC} = 3.3	3V ± 0.3V	V _{CC} =	= 2.7V	V _{CC} = 2	.5 ± 0.2V	Units
Symbol	Parameter	C _L =	50pF	C _L =	50pF	C _L =	30pF	Units
		Min	Max	Min	Max	Min	Max	
t _{PHL}	Propagation Delay	1.5	7.5	1.5	8.5	1.5	9.0	no
t _{PLH}	Data to Output	1.5	7.5	1.5	8.5	1.5	9.0	ns
t _{PZL}	Output Enable Time	1.5	9.0	1.5	10.0	1.5	10.5	
t _{PZH}		1.5	9.0	1.5	10.0	1.5	10.5	ns
t _{PLZ}	Output Disable Time	1.5	7.0	1.5	8.0	1.5	8.4	
t _{PHZ}		1.5	7.0	1.5	8.0	1.5	8.4	ns
t _{OSHL}	Output to Output Skew (Note 6)		1.0					ns
toslh			1.0					115

Note 6: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

Symbol	Parameter	Conditions	V _{CC}	$T_A = 25^{\circ}C$	Units
Cymbol	i didilicio	Conditions	(V)	Typical	Oille
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	0.35	
		$C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$	2.5	0.25	V
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	C _L = 50 pF, V _{IH} = 3.3V, V _{IL} = 0V	3.3	-0.35	
		$C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$	2.5	-0.25	V

Capacitance

Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	$V_{CC} = Open, V_I = 0V \text{ or } V_{CC}$	7.0	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	8.0	pF
C _{PD}	Power Dissipation Capacitance	$V_{CC} = 3.3V$, $V_{I} = 0V$ or V_{CC} , $f = 10$ MHz	25.0	pF

AC LOADING and WAVEFORMS Generic for LCX Family

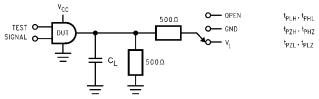
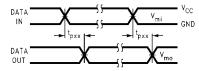
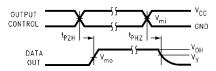


FIGURE 1. AC Test Circuit (C_L includes probe and jig capacitance)

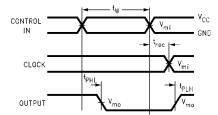
Test	Switch
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6V at $V_{CC} = 3.3 \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$
t_{PZH}, t_{PHZ}	GND



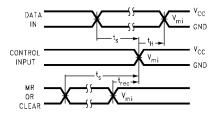
Waveform for Inverting and Non-Inverting Functions



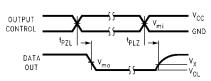
3-STATE Output High Enable and Disable Times for Logic



Propagation Delay. Pulse Width and t_{rec} Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

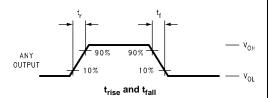
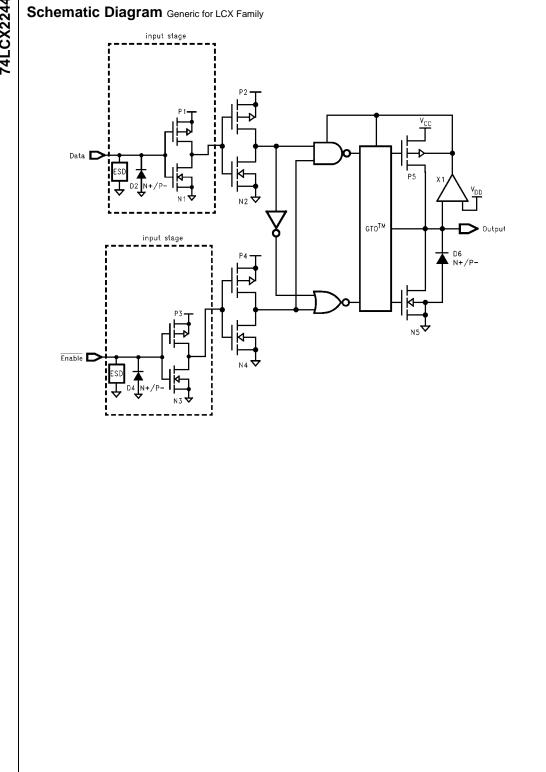
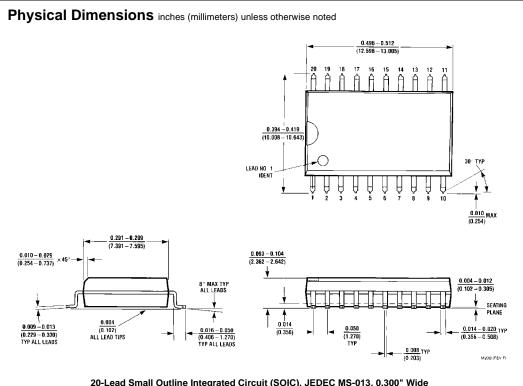


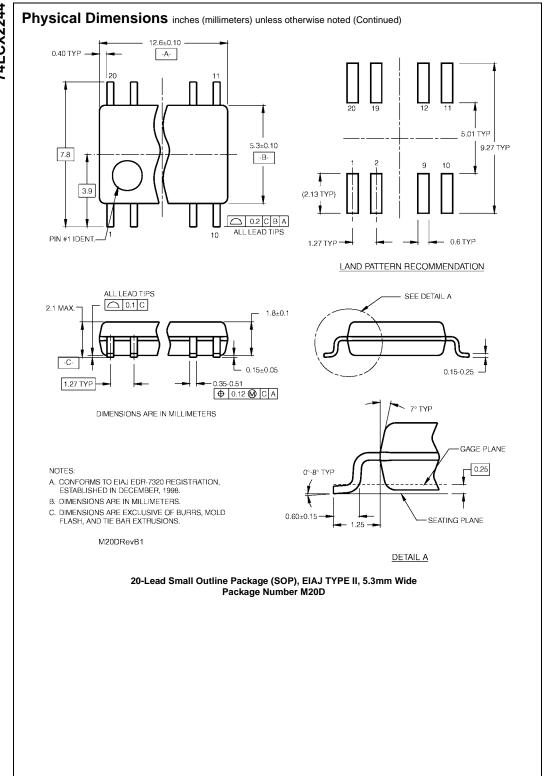
FIGURE 2. Waveforms (Input Characteristics; f =1MHz, $t_r = t_f = 3ns$)

Symbol	V _{cc}		
	3.3V ± 0.3V	2.7V	2.5V ± 0.2V
V _{mi}	1.5V	1.5V	V _{CC} /2
V_{mo}	1.5V	1.5V	V _{CC} /2
V _x	V _{OL} + 0.3V	V _{OL} + 0.3V	V _{OL} + 0.15V
V _v	V _{OH} – 0.3V	V _{OH} – 0.3V	V _{OH} – 0.15V

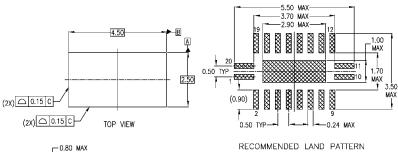


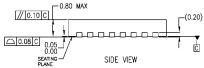


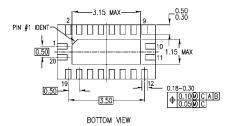
20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide Package Number M20B



Physical Dimensions inches (millimeters) unless otherwise noted (Continued)





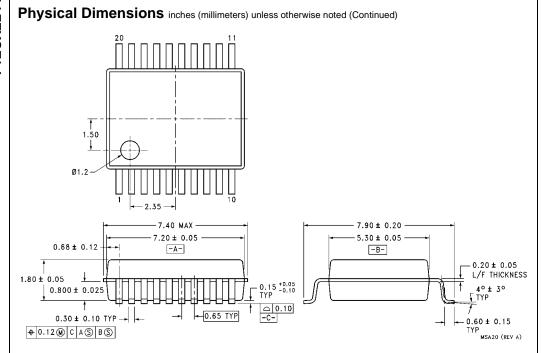


NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-241, VARIATION AC
 B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP020BrevA

20-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 4.5mm Package Number MLP020B (Preliminary)



20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide Package Number MSA20

Physical Dimensions inches (millimeters) unless otherwise noted (Continued) -A-4.16 7.72 4.4±0.1 -B-6.4 3.2 0.2 C B A PIN #1 IDENT LAND PATTERN RECOMMENDATION □ 0.1 C SEE DETAIL A · 0.90^{+0.15} 0.09-0.20 -C-0.1±0.05 0.65 12.00 0.10 M A B C DIMENSIONS ARE IN MILLIMETERS R0.09 MIN GAGE PLANE NOTES: 0.25 A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93. B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND SEATING PLANE TIE BAR EXTRUSIONS. 0.6 ± 0.1 R0.09 MIN D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. 1.00 MTC20RevD1 DETAIL A 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20

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